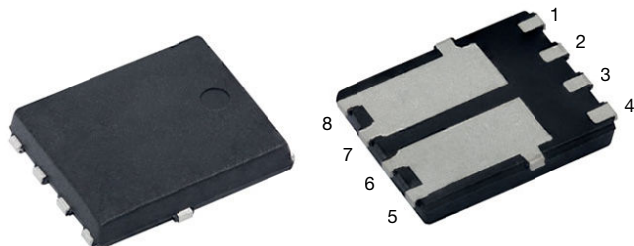


# High Current Density Surface-Mount Trench MOS Barrier Schottky Rectifier

Ultra Low  $V_F = 0.41\text{ V}$  at  $I_F = 2\text{ A}$



**FlatPAK 5 x 6**

1 and / or 2  $\rightarrow$  7, 8  
3 and / or 4  $\rightarrow$  5, 6

## DESIGN SUPPORT TOOLS

[click logo to get started](#)

**3D**  
Models  
Available

## PRIMARY CHARACTERISTICS

$I_{F(AV)}$	2 x 4 A
$V_{RRM}$	60 V
$I_{FSM}$	80 A
$V_F$ at $I_F = 4\text{ A}$ ( $T_A = 125\text{ °C}$ )	0.50 V
$T_J$ max.	175 °C
Package	FlatPAK 5 x 6
Circuit configuration	Separated cathode

## FEATURES

- Trench MOS Schottky technology
- Low forward voltage drop, low power losses
- High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available  
- Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

AUTOMOTIVE  
GRADE  
Available



**RoHS**  
COMPLIANT  
HALOGEN  
FREE

## TYPICAL APPLICATIONS

For use in low voltage high frequency DC/DC converters, freewheeling diodes, and polarity protection applications.

## MECHANICAL DATA

**Case:** FlatPAK 5 x 6

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

## MAXIMUM RATINGS ( $T_A = 25\text{ °C}$ unless otherwise noted)

PARAMETER	SYMBOL	V8KM60DU	UNIT
Device marking code		V8M60D	
Maximum repetitive peak reverse voltage	$V_{RRM}$	60	V
Maximum DC forward current per diode	$I_{F(AV)}^{(1)}$	4	A
	$I_{F(AV)}^{(2)}$	3	A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load per diode	$I_{FSM}$	80	A
Operating junction temperature range	$T_J^{(3)}$	-40 to +175	°C
Storage temperature range	$T_{STG}$	-55 to +175	°C

## Notes

(1) With infinite heatsink

(2) Free air, mounted on recommended pad area

(3) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$



ELECTRICAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage per diode	I <sub>F</sub> = 2 A	T <sub>A</sub> = 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.51	-	V
	I <sub>F</sub> = 4 A			0.56	0.64	
	I <sub>F</sub> = 2 A	T <sub>A</sub> = 125 °C		0.41	-	
	I <sub>F</sub> = 4 A			0.50	0.58	
Reverse current per diode	V <sub>R</sub> = 60 V	T <sub>A</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	-	0.3	mA
		T <sub>A</sub> = 125 °C		1.5	6	
Typical junction capacitance per diode	4.0 V, 1 MHz		C <sub>J</sub>	500	-	pF

**Notes**(1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle(2) Pulse test: pulse width  $\leq 5\text{ ms}$ 

THERMAL CHARACTERISTICS ( $T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Thermal resistance per diode	$R_{\theta JA}^{(1)(2)}$	100	-	$^{\circ}\text{C/W}$
	$R_{\theta JM}^{(3)}$	3.5	4.5	

**Notes**(1) The heat generated must be less than thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ (2) Free air, mounted on recommended copper pad area; thermal resistance  $R_{\theta JA}$  - junction-to-ambient(3) Mounted on infinite heat sink; thermal resistance  $R_{\theta JM}$  - junction-to-mount

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V8KM60DU-M3/H	0.10	H	1500	7" diameter plastic tape and reel
V8KM60DU-M3/I	0.10	I	6000	13" diameter plastic tape and reel
V8KM60DUHM3/H <sup>(1)</sup>	0.10	H	1500	7" diameter plastic tape and reel
V8KM60DUHM3/I <sup>(1)</sup>	0.10	I	6000	13" diameter plastic tape and reel

**Note**

(1) AEC-Q101 qualified

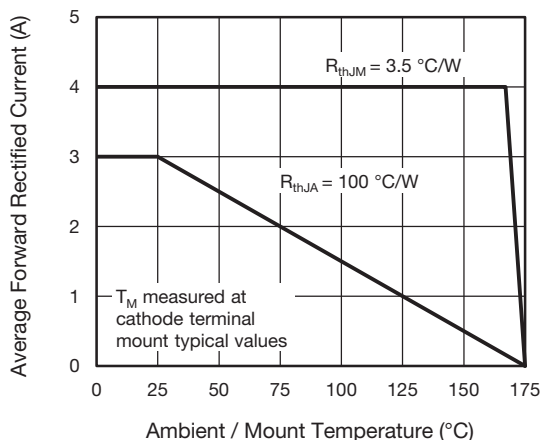
**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)


Fig. 1 - Maximum Forward Current Derating Curve

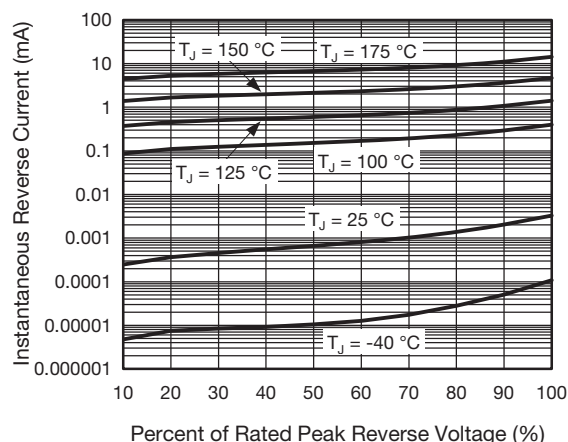


Fig. 4 - Typical Reverse Leakage Characteristics

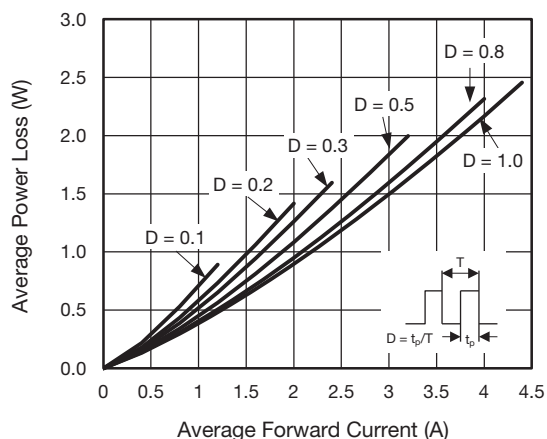


Fig. 2 - Forward Power Loss Characteristics

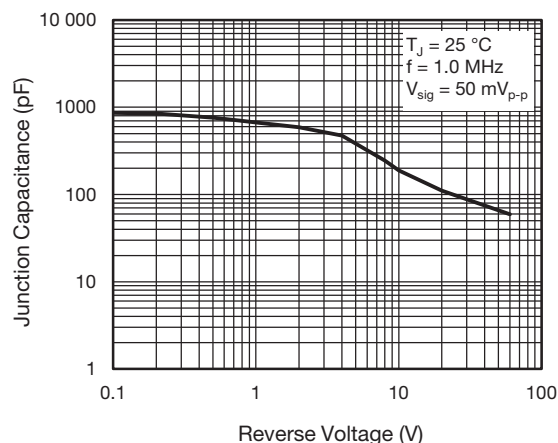


Fig. 5 - Typical Junction Capacitance

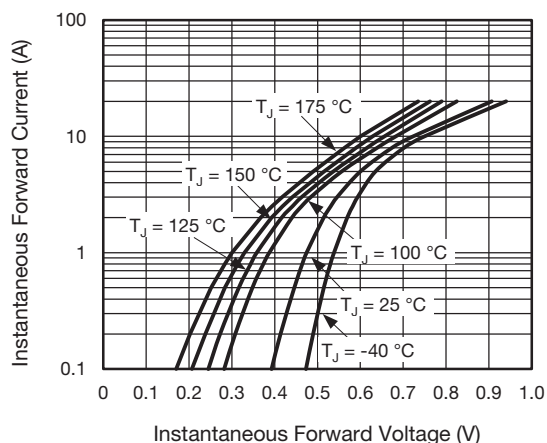


Fig. 3 - Typical Instantaneous Forward Characteristics

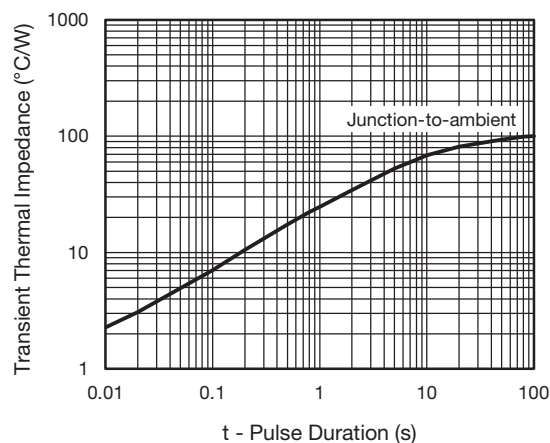
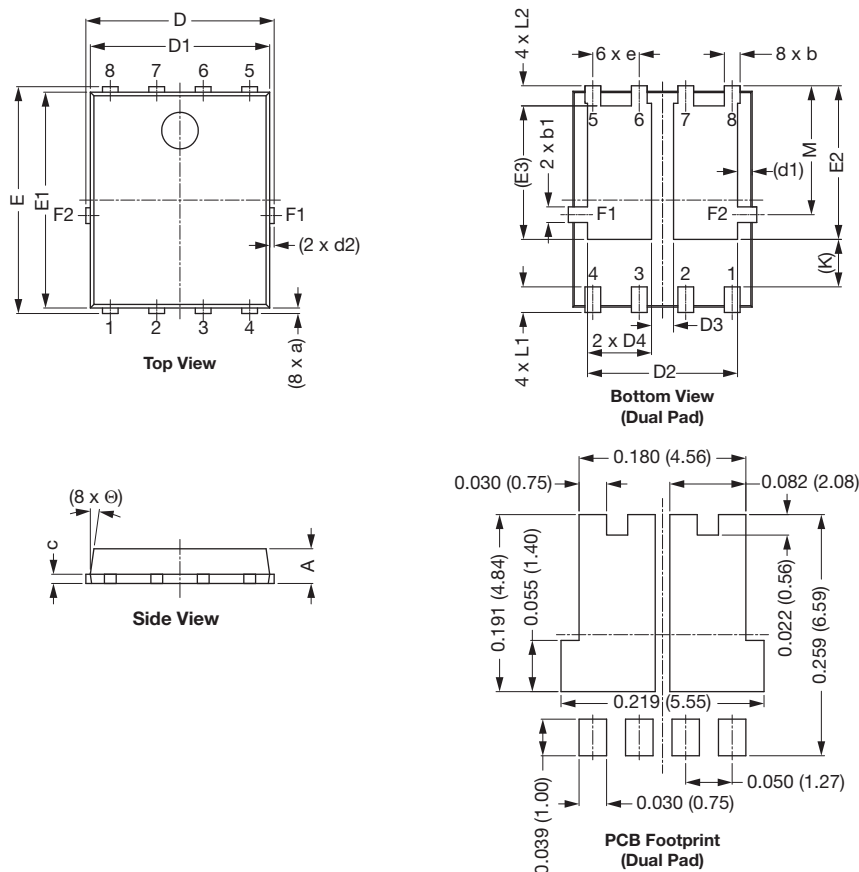


Fig. 6 - Typical Transient Thermal Impedance

**PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)


DIM.	INCHES			MILLIMETERS		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.035	0.039	0.043	0.89	0.99	1.09
(a)	-	0.006	-	-	0.15	-
b	0.013	0.017	0.020	0.32	0.43	0.52
b1	0.013	0.017	0.020	0.32	0.43	0.52
c	0.008	-	0.014	0.20	-	0.35
D	0.197	0.203	0.209	5.00	5.15	5.30
D1	0.189	0.193	0.197	4.80	4.90	5.00
D2	0.154	0.161	0.169	3.90	4.10	4.30
D3	0.020	0.024	0.031	0.50	0.60	0.80
D4	0.063	0.069	0.075	1.60	1.75	1.90
(d1)	-	0.016	-	-	0.40	-
(d2)	-	0.005	-	-	0.125	-
E	0.238	0.244	0.250	6.05	6.20	6.35
E1	0.228	0.232	0.236	5.80	5.90	6.00
E2	0.157	0.165	0.173	4.00	4.20	4.40
(E3)	-	0.144	-	-	3.65	-
e	0.050 BSC			1.27 BSC		
(K)	0.039	-	-	1.00	-	-
L1	0.019	-	0.043	0.48	-	1.10
L2	0.012	-	0.031	0.30	-	0.80
M	0.128	0.138	0.148	3.25	3.50	3.75
Θ	0°	-	10°	0°	-	10°

**Notes**

- Dimensioning and tolerancing per ASME Y14.5-2009
- Dimensions D1 and E1 do not include mold flash or gate burrs
- Dimension (XX) means reference only



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